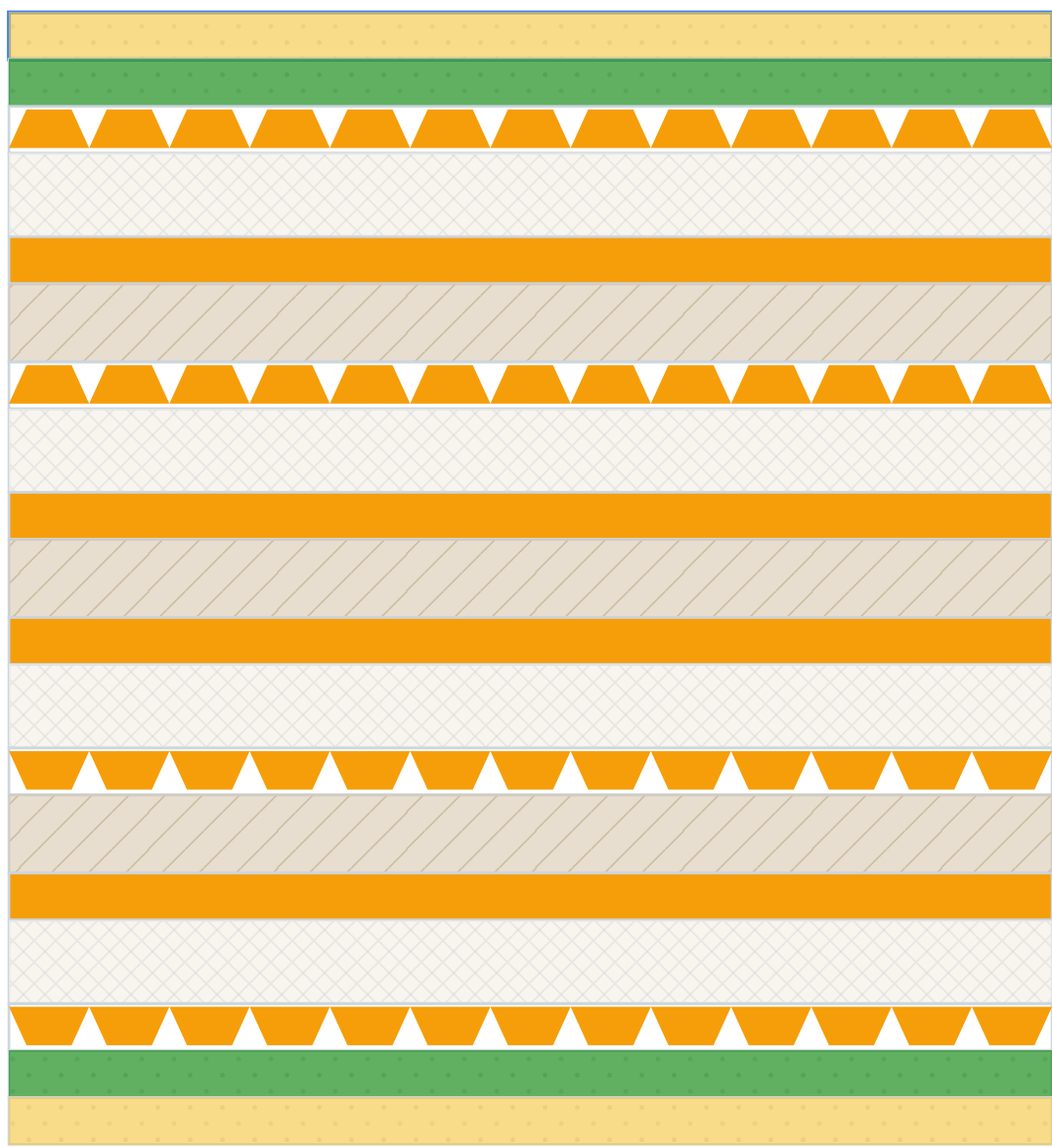


Top Surface Finish
 Top Solder Mask
L1 Signal
 Prepreg
L2 GND
 Core
L3 Signal
 Prepreg
L4 GND
 Core
L5 Power
 Prepreg
L6 Signal
 Core
L7 - GND
 Prepreg
L8 Signal
 Bottom Solder Mask
 Bottom Surface Finish



Spec	Type	Base Thickness	Processed Thickness	RC	DK
ENIG		0.005			
		0.020			
	Signal	0.018	0.018		
FR4 · 2116	Prepreg	0.13	0.1195	52%	4.3
	Plane	0.035	0.035		
FR4	Core	0.23	0.23		4.6
	Signal	0.035	0.035		
FR4 · 7628	Prepreg	0.196	0.175	43%	4.7
	Plane	0.035	0.035		
FR4	Core	0.23	0.23		4.7
	Plane	0.035	0.035		
FR4 · 7628	Prepreg	0.196	0.175	43%	4.7
	Signal	0.035	0.035		
FR4	Core	0.23	0.23		4.5
	Plane	0.035	0.035		
FR4 · 2113	Prepreg	0.13	0.1195	56%	4.2
	Signal	0.018	0.018		
		0.020			
ENIG		0.005			

8 Layer 1.6MM Outer 1OZ RC70

Thickness After Lamination: 1.525 mm
 Finished PCB Thickness: 1.575 mm ±10%
 Inner layer Residual copper ratio: 70%